



Thermoplastic Polyurethan (TPU)

Properties of TPU		Thickness 0.10 mm	Unit	Test method
		Typical Values	Metric	
Adhesive strength TPU/ CU	Copper thickness 18 µm	0.96	N/mm	IPC-TM-650 2.4.9*
Adhesive strength TPU/ FR4	Copper Foil: IPC-4562/3 (HTE FR4 TG150	1.59		
Moisture absorption	37 °C / 80% r.h.	1,23	%	Empirically
Density		1.15	g/cm ³	Empirically
Thermal conductivity		0.17	W/mK	Empirically
Dielectric strength	Dry	91.2	kV/mm	DIN EN 60243-1/2
	72 h in a drying cabinet 85 % r.h.	78.9		
	72 h in a humidity chamber			
Dielectric constant ϵ_r	@ 1 MHZ	4.69		IEC60250
	@ 100 MHZ	4,23		
	@ 1 GHZ	3.31		
Dielectric dissipation factor $\tan \alpha$	@ 1 MHZ	0.086		IEC60250
	@ 100 MHZ	0,094		
	@ 1 GHZ	0.084		
Thermal decomposition		> 250	°C	Empirically
Continuous operating temperature		-20 bis +80	°C	Empirically
Softening area		155 - 185	°C	Empirically
CTE x-y range	Heating rate 3 °C/min	201.8	ppm/K	TMA
Glass transition temperature	Heating rate 3 °C/min	-20	°C	TMA
Hydrolysis resistance		✓		Empirically
Microbe resistance		✓		Empirically
Weldability		✓		Empirically
Thermoforming		✓		Empirically

Reliability Tests STRETCH.flex		Typical Values	Unit	Test method
			Metric	
Washability	25x washing cycles	✓	-	DIN EN ISO 6330 Method 5A
Biocompatible base material		✓	-	ISO 10993-part 5
Resistance in solderability (Reflow)**		✓	-	Empirically

*Based on IPC

** Solder paste: Fa. Indium Indalloy 282

Low temperature solder paste (Sn/Bi)

Drying: 4 hours at 80 °C.

STRETCH.flex Technology is a technology based on stretchable printed circuit boards utilizing tracks made of copper. The common standards (Perfaq, IPC) are not applicable here. All qualification tests are only based on those standards. The suitability for the planned application must be checked by the user before use. The base material, thermoplastic polyurethane, is ROHS listed.